

Corrections

Corrections to “Material Characterization and Warpage Modeling for Power Devices Active Metal Brazed Substrates”

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In [1] below, reference 1 is incorrect. It should read:
A. Sitta, M. Calabretta, M. Renna, and D. Cavallaro, “Solder joint reliability: Thermo-mechanical analysis on power flat packages” in *Advances on Mechanics, Design Engineering and Manufacturing*. Cham, Switzerland: Springer, 2017, pp. 709–716.

Instead of
“Advances on mechanics, design engineering and manufacturing,” in *Proc. Int. Joint Conf. Mech. Design Eng. Adv. Manuf.*, Catania, Italy, Sep. 2016. [Online]. Available: <https://rd.springer.com/book/10.1007/978-3-319-45781-9>

REFERENCE

- [1] G. Mirone, A. Sitta, G. D’Arrigo, and M. Calabretta, “Material characterization and warpage modeling for power devices active metal brazed substrates,” *IEEE Trans. Device Mater. Rel.*, vol. 19, no. 3, pp. 537–542, Sep. 2019.

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